



Material Composition Declaration

EPC2057

Company Name	Efficient Power Conversion (EPC)	Issue Date:	7/8/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	2.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	2.0782	81.5067	84.4426	815067
	Silicon oxide	7631-86-9	0.0149	0.5836		5836
	Silicon nitride	12033-89-5	0.0027	0.1075		1075
	Gallium nitride	25617-97-4	0.0093	0.3656		3656
	Aluminum	7429-90-5	0.0271	1.0636		10636
	Aluminum nitride	24304-00-5	0.0011	0.0438		438
	Titanium	7440-32-6	0.0003	0.0125		125
	Titanium nitride	25583-20-4	0.0013	0.0506		506
	Copper	7440-50-8	0.0005	0.0177		177
	Tungsten	7440-33-7	0.0013	0.0512		512
	Polyimide		0.0163	0.6398	6398	
Under Bump Metal	Titanium	7440-32-6	0.0001	0.0023	0.0115	23
	Copper	7440-50-8	0.0002	0.0092		92
Solder Bump	Copper	7440-50-8	0.0293	1.1476	15.5459	11476
	Nickel	7440-02-0	0.0175	0.6846		6846
	Tin	7440-31-5	0.3434	13.4668		134668
	Silver	7440-22-4	0.0063	0.2468		2468
Sum in total:			2.5497	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.